

SMD SPRING CONTACTS

Kitagawa series: OGSC-(T) and OGSC-(B)

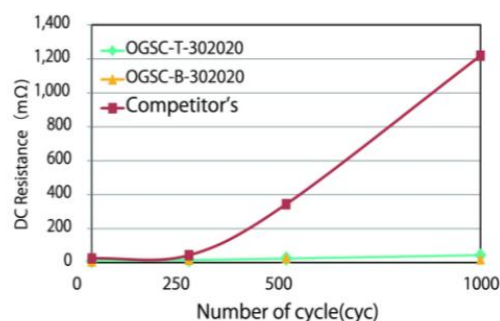
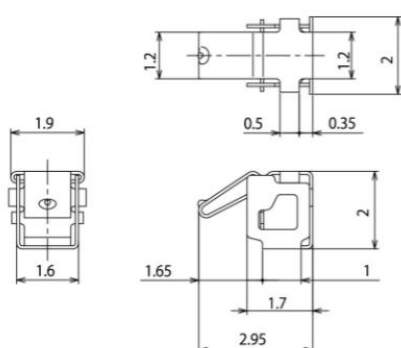


- Ideal for applications where standard grounding between parallel boards/chassis is not possible.
- Ideally suited for use in small devices.
- Operating Temperature: -40°C to +150°C.

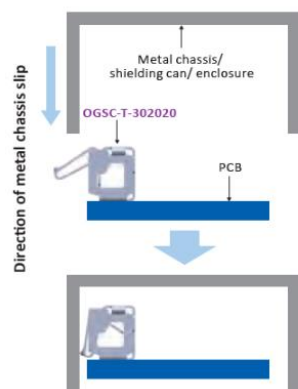
Application Examples

Reel Quantities

Item	OGSC-T-302020	OGSC-B-302020
Applications	Ground contact for SMD	Ground contact for SMD
Material	Corson alloy (t0.08mm)	Corson alloy (t0.08mm)
Surface Treatment	SN reflow plating (underlying Cu plating)	SN reflow plating (underlying Cu plating)
Recommended Operating Temperature °C	-40 ~ 125	-40 ~ 125
Compression Range (mm)	-0.3 ~ 1.0	-0.3 ~ 1.0
Initial Resistance (Ω)	≤0.05	≤0.05
Initial Compression Force (N)	0.2 ~ 3.1	0.4 ~ 3.0



For slipping metal chassis from top
OGSC-T-302020



For slipping metal chassis from bottom
OGSC-B-302020

